

You are cordially invited to attend . . .

NEP/CON '67 EAST

Where you will have the opportunity to . . .

- Learn how your fellow Packaging and Production Engineers and Designers are solving their problems.
- Uncover new components, materials, chemicals, tools, and machines for the building of electronic equipment in NEP/CON's 325 working exhibits.
- Discover the latest techniques for designing the physical structure of electronic equipment and for manufacturing this equipment in quantity.

ONE IDEA PICKED UP AT NEP/CON, FROM THE MANY PRESENTED, CAN SAVE YOUR COMPANY THOUSANDS OF DOLLARS IN PRODUCTION COSTS. AT NEP/CON '67 EAST, THERE WILL BE AT LEAST 1,000 SUCH IDEAS.

NEP/CON is the **only** electronic Conference designed exclusively for engineers who build and produce electronic equipment . . . the men who convert the circuit diagram into the finished product. Every activity at NEP/CON, from the 12 Technical Sessions and 10 Workshops, to the 325 Exhibits, concentrates on the practical application of latest workable techniques and newest products.

YOUR ADMISSION TO THE NEP/CON '67 EAST EXHIBIT FLOOR IS FREE
COMPLIMENTS OF . . .

BARNES DEVELOPMENT CO.

Booth 538

TO GET YOUR FREE ADMISSIONS KIT (VALUE \$4.00), USE THE FORM BELOW.

ADMISSIONS COMMITTEE — NEP/CON '67 EAST — 222 WEST ADAMS STREET, CHICAGO, ILLINOIS 60606

Gentlemen: Please send me my free admission badge (value \$4.00) to the exhibit floor, and information on the technical papers sessions, workshops, and hotel reservations. I understand that there is no obligation involved in requesting this information.

IMPORTANT NOTE: Do **NOT** mail this form after May 31, 1967! Instead, fill it out and bring it to the registration desk at the conference where it will be exchanged for a free admission badge to the exhibit floor, or credited against any Admissions Plan to the technical sessions or workshops.

Name _____ Title _____
Company _____
Address _____
City _____ State _____ Zip _____

- ☐ I certify that I am engaged in packaging/production activities.
- ☐ I supervise _____ people.
- ☐ Please send me _____ additional complimentary ticket applications for other engineers in my department.

I understand that admission badges and tickets are not transferable

Barnes

fill out
and mail
for your

FREE
ADMISSION
BADGE

IDEAS

Circuit Packaging/Production

1,000

here is your FREE TICKET to

HOURS . . .

TECHNICAL SESSIONS — 8:30 A.M. to 12:00 NOON

WORKSHOPS — 4:00 P.M. to 6:30 P.M.

EXHIBITS — 12:00 NOON to 6:00 PM.

NEP/CON TECHNICAL SESSIONS

- Thermal Design in Electronic Equipment
- Connections and Interconnections in Electronic Equipment — I
- Hybrid Circuit Components & Assemblies — I
- Advanced Manufacturing Techniques — I
- Connections and Interconnections in Electronic Equipment — II
- Advanced Manufacturing Techniques — II
- Materials in Electronic Packaging
- Designing Packages and Assemblies for Shock, Vibration Resistance
- Printed Circuit and Multilayer Design Techniques
- Airborne and Spaceborne Equipment Packaging
- Hybrid Circuit Components & Assemblies — II
- Quality Control/Reliability in Electronic Packaging

NEP/CON WORKSHOPS

- Packaging of High-Voltage Circuits
- Mfg. of Thick-Film Microcircuits
- Cleaning Electronic Components
- Bonding Techniques for Hybrid Packages
- Thick Films & Thin Films — Their Differences and similarities
- How to Set Up an In-Plant PC Facility
- Economic Techniques for Automatically Inserting Components into PC Boards
- Thermoelectric Cooling Design
- Photofabrication: The Process and Its Application in the Interconnection and Packaging of Microcircuits
- Precious Metal Plating & Quality Control Procedures for Components

PLACE
STAMP
HERE

NEP/CON '87 EAST

222 West Adams Street, Chicago, Illinois 60606